

Full-Wafer Burn-In & Test System

300 mm Single Touchdown Burn-in and Test of DRAM, FLASH and Logic



SYSTEM BENEFITS:

- **Cost-effective Solution for Producing:**
 - ◆ Known-Good-Die (KGD) for MultiChip Packages
 - ◆ Zero-defect automotive ICs
- **Production Proven Full-Wafer Burn-In Solution:**
 - ◆ Protects wafers and probe cards with individual power channel over-current protection
 - ◆ High volume production capacity – 15 wafers per load
- **Reduces Costs:**
 - ◆ Reduces burn-in times by enabling higher burn-in temperatures
 - ◆ Reduces final test costs by functionally testing wafer during burn-in
 - ◆ Saves packaging costs by deferring until after burn-in
 - ◆ Highly reliable – 4th generation design

“Changing the Way ICs Are Tested”

CORPORATE HEADQUARTERS

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